

REMARKS/ARGUMENT**Regarding the Claims in General:**

Claims 1-14 and 16 are now pending. Claim 15 has been canceled without prejudice and has been rewritten as new claim 16. The other claims have been retained without change.

Regarding the Objection to Claim 15:

This has been addressed by canceling claim 15 and substituting new independent claim 16 which explicitly recites structural elements of a semiconductor device. The only element expressly recited in claim 9 is the wire bond.

Regarding the Prior Art Rejections:

In the outstanding Office Action, claims 1-15 were rejected under 35 U.S.C. 102(e) as being anticipated by Ismail et al Published U.S. Application 2003/0230796 (Ismail). Reconsideration and withdrawal of this rejection is respectfully requested in view of the comments below.

Claim 1 reads:

“A method of forming a wire bond bonding a wire to a connection pad of an electronic device, comprising the steps of forming a first stitch bond on the connection pad, and forming a second stitch bond on the connection pad that is contiguous with the first stitch bond.”

In Ismail, the first and second stitch bonds are neither formed on the connection pad nor is the second stitch bond contiguous with the first stitch bond. In particular, the Examiner refers to Fig. 6, which illustrates stitch bonds formed at the end of wires 74, 78, 82 which are separated by bumps 76, 80. The first stitch bond at the end of wire 74 is formed on top of a ball bump 72, and not on the connection pad 70. “On” is defined in the Merriam-Webster Online Dictionary as “a function word to indicate position in contact with and supported by the top surface of.”

In fact, paragraph [0030] of Ismail states clearly that “the bond pad 70 has a first bump 72 disposed on its surface. A first wire 74 is stitch bonded to the first bump 72 with a first stitch bond.” Thereafter, “a second bump 76 is formed on the first stitch bond. A second wire 78 is stitch bonded

to the second bump 76 with a second stitch bond." The second stitch bond is therefore not formed on the connection pad as there is no contact between it and the bond pad 70.

Furthermore, the second stitch bond is not contiguous with the first stitch bond because it is separated from the first stitch bond by a second bump 76. "Contiguous" is defined as touching or connected throughout in an unbroken sequence." (See the Merriam-Webster Online Dictionary).

Similarly, in the case of claim 2, the second stitch bond in Ismail cannot partially lie on the connection pad because it does not contact the bond pad 70 at all.

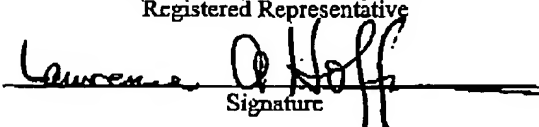
The Examiner is respectfully reminded that the present invention is different from the ball stitching on bond (BSOB) approach employed by Ismail, which has the disadvantages set out at page 2, line 31 to page 3, line 18 of the present application.

It is respectfully submitted that the Examiner has adopted an overly broad definition of "on the connection pad" and "contiguous." He has taken "on" to include bonds made "over" the bond pads which have no contact therewith, and "contiguous" to mean an electrical connection although separated. These are not valid interpretations in view of the disclosure. Upon a proper interpretation, it is clear that Ismail does not anticipate the claims herein.

Claims 2-9 are dependent on allowable claim 8, and claims 10-14 are dependent on allowable claim 9. These claims are therefore also allowable for the reasons stated above. In addition, these claim recite features which, in combination with the features of their respective parent claims are not disclosed, taught, or suggested in Ismail.

In view of the foregoing, favorable reconsideration and allowance of this application are respectfully solicited.

I hereby certify that this correspondence is being transmitted by Facsimile to (571) 273-8300 addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below.

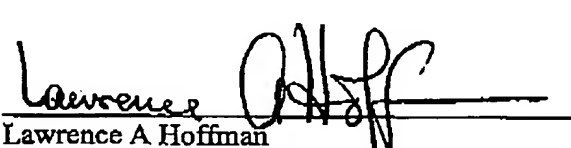
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Name of applicant, assignee or
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April 5, 2006
Date of Signature

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Respectfully submitted,



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